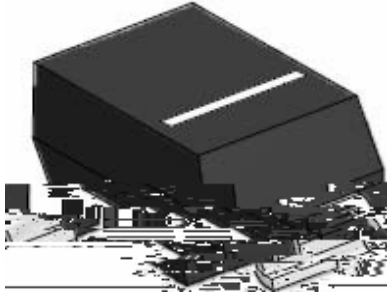


High Speed Switching Diode



Features

V_R 75V
 I_{FAV} 200mA

Typical Applications

Extreme fast switches

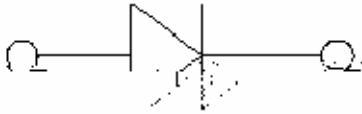
Mechanical Data

Package: SOD-323

Terminals: Tin plated leads, solderable per J-STD-002 and JESD22-B102

Polarity: Cathode line denotes the cathode end

Marking: T4



Maximum Ratings ($T_a=25$ Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Conditions	VALUE
Repetitive peak reverse voltage	V_{RRM}	V		75
Peak forward surge current	I_{FSM}	A	$t_p=10\mu s$	2
Average forward current	I_{FAV}	mA		200
Power dissipation	P_{tot}	mW		350
Thermal Resistance	R_{thJA}	/W		315
Maximum junction temperature	T_j			-55 ~ +150
Storage temperature range	T_{stg}			-55 ~ +150

Electrical Characteristics ($T_a=25$ Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Conditions	Min	Typ	Max
Maximum Forward voltage	V_F	V	$I_F=1mA$			0.715
	V_F	V	$I_F=10mA$			0.855
	V_F	V	$I_F=50mA$			1.0
	V_F	V	$I_F=150mA$			1.25
Minimum Breakdown voltage	I_R	μA	$V_R=75V$			1.0
	V_R	V	$I_R=100\mu A$	100		
	t_r	ns	$I_F=10mA, I_{rr}=0.1I_R, R_L=100$			6

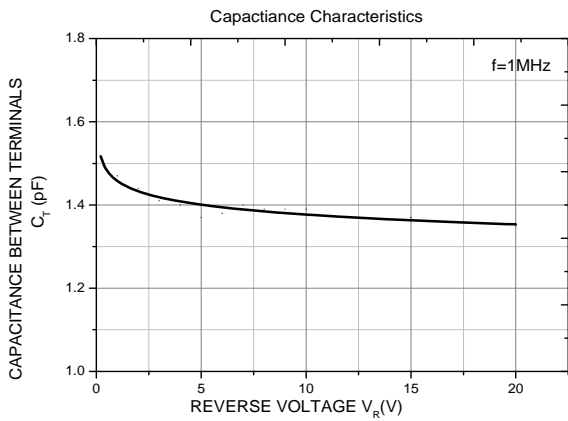
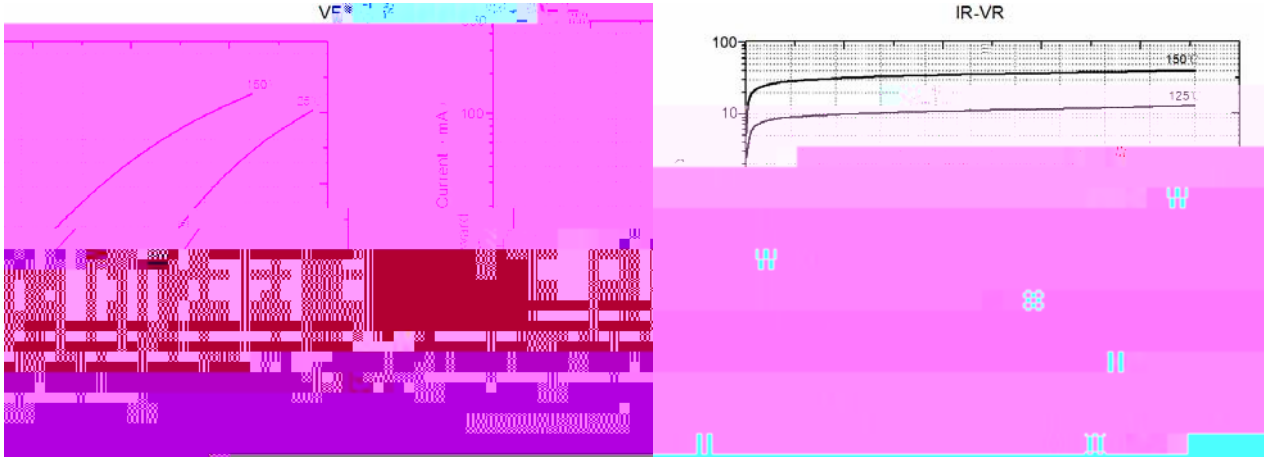


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Ordering Information (Example)

PREFERED P/N	PACKING CODE	UNIT WEIGHT(g)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
BAS16WS	F2	Approximate 0.0048	3000	30000	120000	7" reel

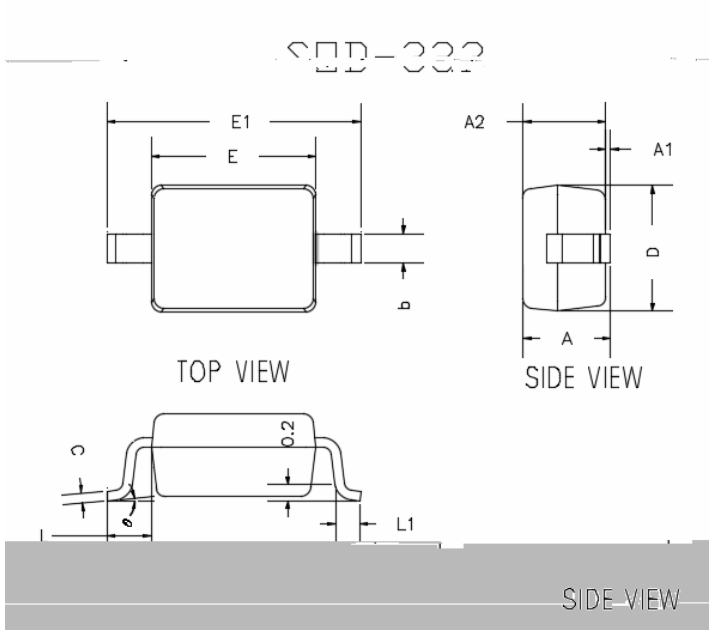
Characteristics (Typical)





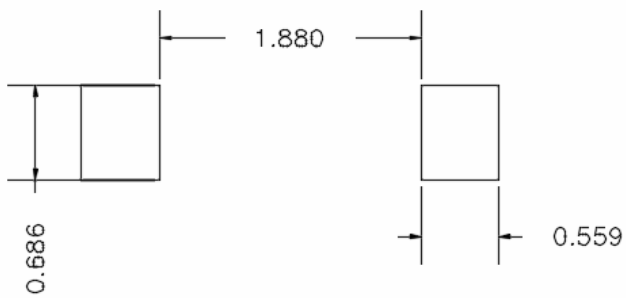
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Outline Dimensions



DIM	DIMENSIONS			
	INCHES		MM	
	MIN	MAX	MIN	MAX
A	---	0.0393	---	1.0000
A1	0.0000	0.0039	0.0000	0.1000
A2	0.0314	0.0354	0.8000	0.9000
b	0.0098	0.0157	0.2500	0.4000
D	0.0031	0.0059	0.0800	0.1500
E	0.0472	0.0551	1.2000	1.4000
E1	0.0629	0.0709	1.6000	1.8000
L	0.0187TYP		0.475TYP	
L1	0.0098	0.0157	0.250	0.400
θ	0°	8°	0°	8°

Soldering Footprint



UNIT: mm

SUGGESTED SOLDER PAD LAYOUT



BAS16WS

Disclaimer

The information presented in this document is for reference only. Yangzhou Yangjie Electronic Technology Co., Ltd. reserves the right to make changes without notice for the specification of the products displayed herein to improve reliability, function or design or otherwise.

The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with